WHAT IS CLAIMED IS:

1. A thin-film magnetic head comprising:

magnetic layers each containing two or more elements of Co, Ni, and Fe;

wherein said magnetic layers are plated films, and a magnetic layer, of said magnetic layers, which is disposed near a magnetic gap is a plated magnetic film containing Co, Ni, and Fe, with $20 \leqq Co \leqq 40$ wt%, $0 < Ni \leqq 2$ wt%, and $60 \leqq Fe \leqq 80$ wt%, and having a saturation magnetic flux density of 23,000 gauss or more.

2. A process for production of a thin-film magnetic head with magnetic layers each containing two or more elements of Co, Ni, and Fe,

wherein said magnetic layers are formed by electroplating in a plating bath having a pH value of 2 or less, and

a magnetic layer, of said magnetic layers, which is disposed near a magnetic gap is a plated magnetic film containing Co, Ni, and Fe, with $20 \leqq Co \leqq 40$ wt%, $0 < Ni \leqq 2$ wt%, and $60 \leqq Fe \leqq 80$ wt%, and having a saturation magnetic flux density of 23,000 gauss or more.

3. A process as in 2, wherein the magnetic layers are formed in a plating bath containing saccharin sodium as a stress relaxing agent.

4. A process for production of a thin-film magnetic head as defined in claim 3, wherein the plating bath contains saccharin sodium in an amount of 0.5-2 g/L.

5. A thin-film magnetic head of write-read separate type in which a read element is a magneto-resistive effect element and a write element is an inductive magnetic head,

wherein upper and lower magnetic cores of a write head partly or entirely have magnetic layers consisting of magnetic films each containing two or more elements of Co, Ni, and Fe, the magnetic films are plated films, a magnetic layer, of the magnetic layers, which is disposed near a magnetic gap is composed of a plated magnetic film containing CoNiFe, with $20 \leqq Co \leqq 40$ wt%, $0 < Ni \leqq 2$ wt%, and $60 \leqq Fe \leqq 80$ wt%, and having a saturation magnetic flux density of 23,000 gauss or more, and the plated magnetic film is a soft magnetic thin film formed by electroplating in a plating bath having a pH value of 2 or less.